Call for Papers

ICEP 2019

2019 International Conference on Electronics Packaging

April 17-20, 2019
Toki Messe, Niigata, Japan
Sponsored by JIEP, IEEE EPS Japan Chapter and IMAPS

Major Topics

Advanced Packaging
2.5D/3D, Advanced CSP and POP, Advanced Flip-Chip, Automotive, Embedded and Advanced Substrates, Fan-Out, Heterogeneous Integration and SiP, High Performance Computing and Data Center, Interposers, Temporary Bonding/De-Bonding, TSV/TGV, Wafer Level & Panel Level Process, Wafer Level Packaging, Wearable & IoT, Wireless Interconnection

Design, Modeling, and Reliability
Advanced Package Reliability (TSV/TGV, 2.5D/3D Packaging, WCSP, Fan-Out, Embedded Technologies), Automotive Reliability Requirements, Challenges in SiP Reliability, Drop and Dynamic Mechanical Reliability, Failure Analysis Techniques and Materials Characterization, Fracture and Warpage in Packages, High Voltage Packaging and IoT Reliability, High-Speed Board Design, Interconnect Reliability (Flip-Chip, Wire-Bond), Mechanical Design and Reliability, Physics of Failure, Probabilistic Design for Reliability (PDfR), Reliability Test Methods and Life Models, Signal and Power Integrity, System Level Reliability (Testing, Modeling), TCAD

Emerging Technologies
3D Printing, Anti-Counterfeiting, Bendable electronics, Biomimetics, Biosensors, Compact & Autonomous Sensor Packaging, Components for Internet of Things (IoT) and Smart Electronics, Device Applications, Disposable/Dissolvable Packaging, Flexible electronics, Future diagnostic and treatment solutions, Hearing aids, Heterogeneous Integration, Implantable defibrillators, Implantable Device Packaging, Inkjet, Interventional catheters, Materials and Approaches to Interconnects and Packaging, Medical Electronics, Micro opto electro mechanical systems (MOEMS), Microelectromechanical systems (MEMS), Microfluidics, Nano Imprint, Nano-Battery, Nanoelectromechanical systems (NEMS), Neurostimulator and drug delivery, New Additive Packaging Process Technologies and Materials, New Materials and Methods for Packaging Microfluidics, Novel Substrates, Organic Semiconductors, Packaging for Wireless, Photovoltaic, Pillcams, Redundancy, Repair, Security, Self-Alignment and Assembly, Self-Healing, Sensor Devices, Stretchable electronics, Structural Electronics, Ultrasound transducers, Wafer Level Integrated Silicon Photonics, Wearable Electronics, Wireless communications

High-Speed, Wireless & Components
3D Printed RF Components and Modules, 5G, Advanced Components (Materials, Structures), Ambient Intelligence, Antennas, Automotive Sensors, Beamforming, Design and Analysis of Power Delivery Systems, Electrical Modeling and Design, EMI, Fabrication and Characterization, Filters, Flexible Electronics, Full Duplex, High-Speed, High-Speed Data Transfer/ Communications, High-Speed Systems (Design, Analysis), Imagers, Integrated Voltage Regulators (IVR), LTE, M2M Platforms, Massive MIMO, Microwave, Millimeter Wave, Mixed-Signal, mm Wave and THz T/R Modules, Modules & Sub-Systems, Power and Signal Integrity, Power Management, Proximity Sensors, Radars, RF, RF to THz Devices & Passive Components, RFID and Tagging, RF-MEMS, RF-Opto, Small Cell, Wearable and Sensor Technologies for Internet of Things (IoT), Wireless Power, Wireless Sensor and Computing Nodes, WLAN

Interconnections
2.5D/3D, Automotive, Conductive Adhesives, Embedded Multi-die Interconnect Bridge, Embedded Systems, Energy Harvesting, Fan-Out and Fan-In, Flip-Chip (Bonding, Materials, Reliability), Harsh Environments, IMC Interconnect, Interconnects for Bio-Medical, RDL, Si/Glass/Organic Interposers, Solder Bumping and Cu Pillar, Thermal/Mechanical/Electrical Tests & Reliability, TSV/TGV (Fabrication, Characterization, Reliability), Wafer Level & Panel Level Interconnects, Wearables, Wirebonds (Process, Reliability), WLCSP

Materials and Processes
3D Materials & Processing, 3D Materials and Processing, Advanced Assembly Technology Solutions, Advancement in 3D Handling & Packages, Advances in RF Materials & Components, Battery Materials, Carbon Electronics, Dicing and Singulation, Embedded/Hybrid Package Manufacturing Process, Emerging Electronic Materials, Enhancement in Thermal Compression Bonding Processes, Flexible and Wearable Electronics, Healthcare/Fitness Component Assembly, Large/Ultra Large Package (SiP, SIM, MCP) Integration and Processing, Next Generation Packaging Substrates, Next Generation Substrates for Package Integration, Novel Assembly Technologies, Novel Fan-Out Interconnections, Novel Interconnect Materials, Optoelectronic Materials, Panel Level Manufacturing for WLP, Panel Processing & Materials, Performance Enhanced Materials (Adhesives, Underfills, TIMs, Dielectrics, Molding Compounds, Solder, Temporary Bond), Performance Enhanced Materials (Prepregs, Plating solution, Photoresist), Performance Enhanced Printing Wiring Board (Fine line, Low CTE, Coreless, Thin Core), Thin Die/Thin Mold/Thin Package Handling and Assembly, Via Formation and Filling, Wafer Level Packaging, Warpage Control/Management in Board Level Assembly, Wearable/IoT Package Assembly

Optoelectronics
3D Photonics, Advanced Optical Connectors, High-Efficiency LEDs and High Power Lasers, Integrated Optical Sensors, Integrated Photonics Modules, Materials and Manufacturing Technology, Mid-Board/On-Board Optical Modules, Optical Chip-Scale and Heterogeneous Integration, Optical Interconnects, Optical Printed Circuit Board, Optical Waveguide Circuits, Optoelectronic Assembly and Reliability, Transceivers and Silicon Photonic Modules

Power Electronics Integration
AC-DC Converters, Capacitors / Supercapacitors, DC-DC Converters, Devices and Components, Fast Recovery Diodes, GaN HEMTs, Hybrid System, Interconnects and Fuses, Inverters/converters for electric vehicles, Lamp Ballasts and LED Lighting, Magnetic materials and components, Mechatronic Integration, Motor Drives and Inverters, Packaging of high-temperature power electronics, Power Electronics for Utility Interface, Power Module, Power Silicon MOSFETs / BJTs / IGBTs, Sensors, SiC MOSFETs and BJTs, Systems and Components Reliability, Ultra High Power Density Integration

Thermal Management
Advanced Cooling Modules, Fans and Blowers, Heat Pipes, Heat Sinks, Micro and Nano Scale Heat Transfer, Thermal Issues in Devices, Thermal Measurements

詳細は、裏面参照下さい

アブストラクト・論文提出のスケジュール

アブストラクト受付　　　：2018年　8月中旬から投稿可
アブストラクト提出　〆切　：2018年10月31日
採択通知連絡　　　　　　：2018年12月13日
論文提出　〆切　　　　　：2019年　2月14日

アブストラクトは、web掲載のテンプレートをご使用下さい。
http://www.jiep.or.jp/icep/

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Outstanding Technical paper に選ばれた論文は、JIEP規定に基づき表彰されます。
表彰対象は、発表者である著者と共著者です。

受賞資格:
発表者が著者もしくは共著者であること。
4から6ページの論文が期限内に投稿されていること。

IEEE EPS Japan Chapter Young Awards

優秀な論文発表した若い技術者・研究者に対して、IEEE EPS Japan Chapterの規定基づき表彰されます。

受賞資格:
筆頭著者でかつ実際に発表者であること。
2019年の12月31日時点で、年齢が満35歳未満であること。
授賞時に、IEEE会員およびEPS会員であること。
Young Awardの過去受賞者でないこと。
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ICEPについて

ICEPは、2001年に始まり、エレクトロニクスパッケージング分野における国内開催の国際会議としては、最も大きな国際会議の一つです。例年、300から500名の参加者を動員し、約35の技術セッションスロットを世界中のエキスパートの参加も交え開催されております。
ICEPは、皆様の技術講演の場とグローバルネットワーキングの機会を提供いたします。
エレクトロニクス実装学会の主催、IEEE EPS (Electronics Packaging Society) Japan ChapterとiMAPSに共催されております。

参加費

JIEP, IEEE, IMAPS会員	41,000円(論文集・Reception・消費税含む)
非会員	55,000円(論文集・Reception・消費税含む)
学　生	12,000円(論文集・Reception・消費税含む)

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スポンサー募集

ICEP2019では、各種カテゴリーでスポンサーを募集いたします。
HP・休憩時のスクリーンへの会社名・ロゴの表示、Proceedingsへのロゴ掲載、機器展示等、各種特典がございます。
詳細は以下のサイトをご参照下さい。
http://www.jiep.or.jp/icep/ICEP2019_sponsor_Japanese.pdf

是非ともこの機会に、ご検討ください。

お問い合わせ

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